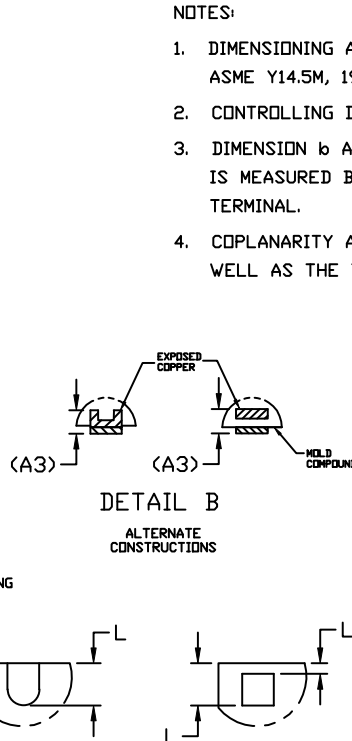
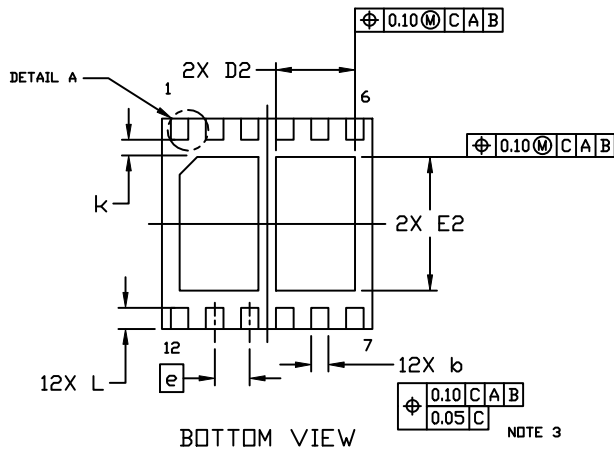
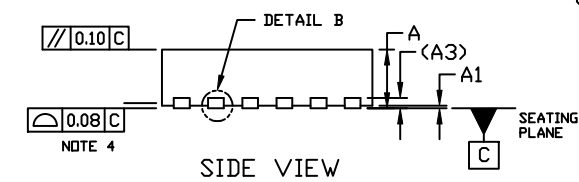
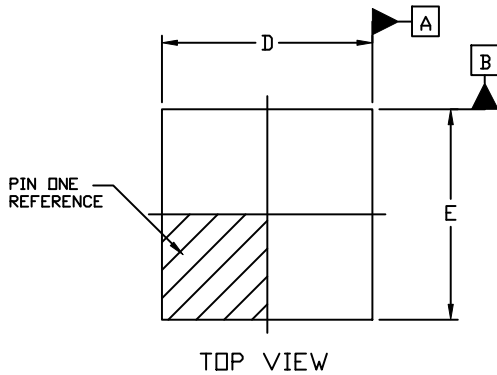


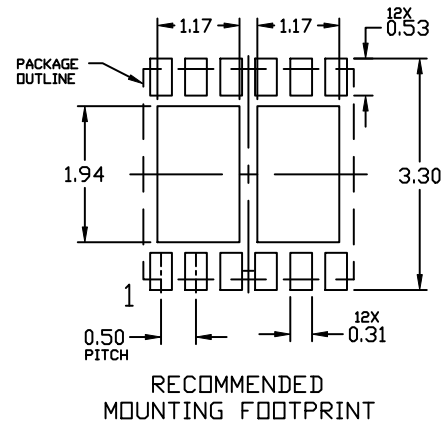


DFN12 3x3, 0.5P
CASE 506EN
ISSUE O

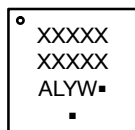
DATE 27 SEP 2018



DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.80	0.90	1.00
A1	0.00	—	0.05
A3	0.20 REF		
b	0.20	0.25	0.30
D	2.90	3.00	3.10
D2	1.03	1.13	1.23
E	2.90	3.00	3.10
E2	1.80	1.90	2.00
e	0.50 BSC		
k	0.20	—	—
L	0.20	0.30	0.40
L1	—	—	0.15



GENERIC MARKING DIAGRAM*



- XXXX = Specific Device Code
- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

(Note: Microdot may be in either location)

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DESCRIPTION:	DFN12 3x3, 0.5P	PAGE 1 OF 1

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